

CHIP-MOUNTED CONTACT SPRINGS

ABSTRACT OF THE DISCLOSURE

5 Bonding wire is formed into an inverted "V" shape by bonding both ends of a bonding wire to adjacent points on an integrated circuit, the vertex of the "V" shape forming a contact point for contacting another integrated circuit, or other device. One end of the bonding wire is bonded to a specified point on the integrated circuit, the bonding head is raised, and then lowered to an immediately adjacent point to effect the second bonding, thus forming the inverted
10 V shape. This V shape, being bonded at both ends, is mechanically stable, is resilient in form, and allows for the use of resilient, or non-resilient bonding wire. The vertex of the V shape forms a point or surface for contacting another integrated circuit, or other device, for communicating signals to and from the device to which the bonding wire is bonded.

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